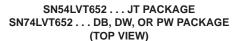
SCBS141E - MAY 1992 - REVISED JULY 1995

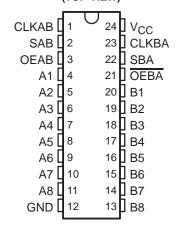
- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low-Static Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Bus-Hold Data Inputs Eliminate the Need for External Pullup Resistors
- Support Live Insertion
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), and Ceramic (JT) DIPs

description

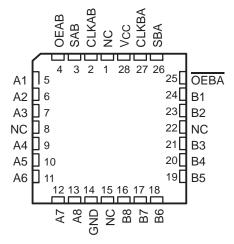
These bus transceivers and registers are designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

The 'LVT652 consist of bus transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers.





SN54LVT652 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

Output-enable (OEAB and OEBA) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between real-time and stored data. A low input selects real-time data and a high input selects stored data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'LVT652.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SCBS141E - MAY 1992 - REVISED JULY 1995

description (continued)

Data on the A or B data bus, or both, can be stored in the internal D-type flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs regardless of the select- or enable-control pins. When SAB and SBA are in the real-time transfer mode, it is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input; therefore, when all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last state.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

The SN74LVT652 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54LVT652 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74LVT652 is characterized for operation from -40° C to 85° C.

FUNCTION TABLE

		INPU ⁻	rs			DATA	A 1/0†	ODERATION OR FUNCTION
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1-A8	B1-B8	OPERATION OR FUNCTION
L	Н	H or L	H or L	Х	Х	Input	Input	Isolation
L	Н	\uparrow	\uparrow	X	X	Input	Input	Store A and B data
Х	Н	\uparrow	H or L	X	X	Input	Unspecified [‡]	Store A, hold B
Н	Н	\uparrow	\uparrow	X‡	X	Input	Output	Store A in both registers
L	X	H or L	\uparrow	X	X	Unspecified [‡]	Input	Hold A, store B
L	L	\uparrow	\uparrow	X	χ‡	Output	Input	Store B in both registers
L	L	Χ	Χ	X	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	X	Н	Output	Input	Stored B data to A bus
Н	Н	Χ	Χ	L	X	Input	Output	Real-time A data to B bus
Н	Н	H or L	Χ	Н	X	Input	Output	Stored A data to B bus
Н	L	H or L	H or L	Н	Н	Output	Output	Stored A data to B bus and stored B data to A bus

[†] The data output functions may be enabled or disabled by a variety of level combinations at the OEAB or OEBA inputs. Data input functions are always enabled; i.e., data at the bus pins is stored on every low-to-high transition of the clock inputs.

Select control = H; clocks must be staggered in order to load both registers



[‡] Select control = L; clocks can occur simultaneously

SCBS141E - MAY 1992 - REVISED JULY 1995

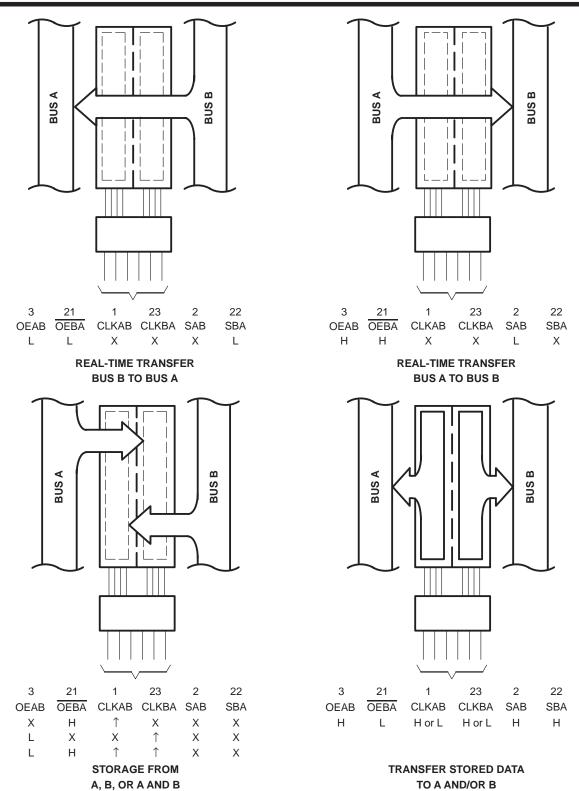


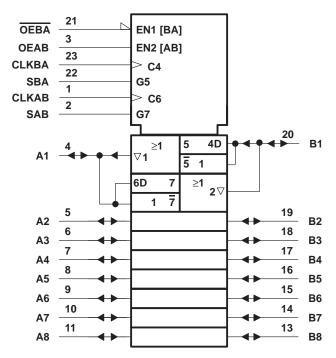
Figure 1. Bus-Management Functions

Pin numbers shown are for the DB, DW, JT, and PW packages.



SCBS141E - MAY 1992 - REVISED JULY 1995

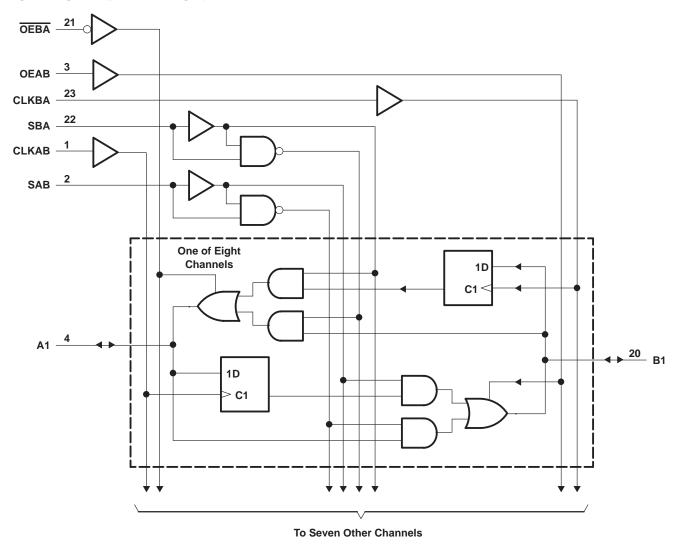
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, and PW packages.



logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, and PW packages.

SCBS141E - MAY 1992 - REVISED JULY 1995

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	. −0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V _O (see Note 1)	0.5 V to 7 V
Current into any output in the low state, IO: SN54LVT652	96 mA
SN74LVT652	128 mA
Current into any output in the high state, IO (see Note 2): SN54LVT652	48 mA
SN74LVT652	64 mA
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Maximum power dissipation at T _A = 55°C (in still air) (see Note 3): DB package	0.65 W
DW package	1.7 W
PW package	0.7 W
Storage temperature range, T _{stq}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
 - The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.
 For more information, refer to the Package Thermal Considerations application note in the 1994 ABT Advanced BiCMOS Technology Data Book. literature number SCBD002B.

recommended operating conditions (see Note 4)

			SN54L	VT652	SN74L		
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		2.7	3.6	2.7	3.6	V
VIH	High-level input voltage		2	EN	2		V
VIL	Low-level input voltage			0.8		0.8	V
٧ _I	Input voltage		,4	5.5		5.5	V
loh	High-level output current		Ç	-24		-32	mA
lOL	Low-level output current		200	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	Sp.	10		10	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.

SCBS141E - MAY 1992 - REVISED JULY 1995

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	_	SN	154LVT6	52	SN						
PARAMETER	TE TE	EST CONDITIONS		MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT	
VIK	$V_{CC} = 2.7 \text{ V},$	$I_{I} = -18 \text{ mA}$				-1.2			-1.2	V	
	$V_{CC} = MIN \text{ to } MAX^{\ddagger},$	$I_{OH} = -100 \mu\text{A}$		VCC-C).2		VCC-C).2			
	V _{CC} = 2.7 V,	$I_{OH} = -8 \text{ mA}$		2.4			2.4			V	
VOH	V 2.V	I _{OH} = - 24 mA	2						V		
	VCC = 3 V	$I_{OH} = -32 \text{ mA}$				2					
	\/ 0.7\/	$I_{OL} = 100 \mu A$				0.2			0.2		
	V _{CC} = 2.7 V	I _{OL} = 24 mA				0.5			0.5		
V		I _{OL} = 16 mA				0.4			0.4	V	
V _{OL}	\/ 2\/	I _{OL} = 32 mA			0.5			0.5	V		
	V _{CC} = 3 V	I _{OL} = 48 mA			0.55						
		I _{OL} = 64 mA		4	N.			0.55			
	V _{CC} = 3.6 V,	$V_I = V_{CC}$ or GND	Control inputs		3	±1			±1		
	$V_{CC} = 0$ or MAX ‡ ,	$V_1 = 5.5 V$			Q.	10			10		
lį	V _{CC} = 3.6 V	V _I = 5.5 V			5	20			20	μΑ	
		VI = VCC	A or B ports§		3	5			5		
		V _I = 0	8		-10			-10			
l _{off}	$V_{CC} = 0$,	V_{1} or $V_{0} = 0$ to 4.5	5 V	- V					±100	μΑ	
lia i n	\/ 2\/	V _I = 0.8 V	A or D porto	75			75			^	
l(hold)	VCC = 3 V	V _I = 2 V	A or B ports	-75			-75			μΑ	
IOZH	V _{CC} = 3.6 V,	VO = 3 V				1			1	μΑ	
lozL	$V_{CC} = 3.6 \text{ V},$	$V_0 = 0.5 V$				-1			-1	μΑ	
			Outputs high		0.13	0.19		0.13	0.19		
Icc	$V_{CC} = 3.6 \text{ V},$	$I_{O} = 0$,	Outputs low		8.8	12		8.8	12	mA	
icc	V _I = V _{CC} or GND		Outputs disabled		0.13	0.19		0.13	0.19	1117 (
ΔI _{CC} ¶	V _{CC} = 3 V to 3.6 V, Other inputs at V _{CC} or	– 0.6 V,			0.2			0.2	mA		
C _i	V _I = 3 V or 0							4.5		pF	
C _{io}	V _O = 3 V or 0				11			11		pF	

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 $[\]$ Unused terminals at \mbox{V}_{CC} or GND

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

SCBS141E - MAY 1992 - REVISED JULY 1995

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

				SN54LVT652				SN74LVT652				
				3.3 V 3 V	V _{CC} =	2.7 V	V _{CC} =	3.3 V 3 V	V _{CC} =	2.7 V	UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
fclock	Clock frequency		0	150	0	150	0	150	0	150	MHz	
t _W	Pulse duration, CLK high or low				JCN		3.3		3.3		ns	
	Setup time, A or B before	Data high		20)	N.E.		1.2		1.2			
tsu	CLKAB↑ or CLKBA↑	Data low		6,6			2		2.5		ns	
th	Hold time, A or B after CLKAB↑ or CLKBA↑						0.5		0.5		ns	

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 2)

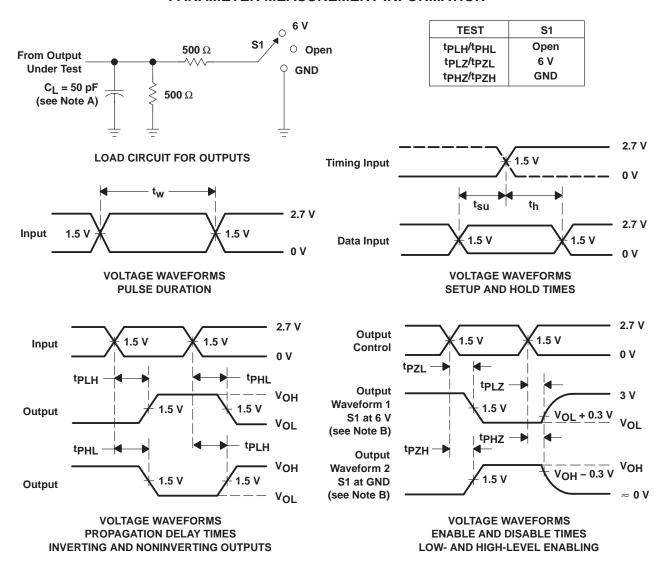
			SN54LVT652										
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		Vo	± 0.3 V	V	V _{CC} = 2.7 V		UNIT	
			MIN	MAX	MIN	MAX	MIN	TYP†	MAX	MIN	MAX		
f _{max}							150			150		MHz	
t _{PLH}	CLKBA or	A or B					1.8	3.7	6		6.9		
^t PHL	CLKAB	AOIB					2	3.7	5.7		6.4	ns	
t _{PLH}		D A			N3		1.2	2.8	4.7		5.5		
t _{PHL}	A or B	B or A			13		1	2.6	4.6		5.3	ns	
t _{PLH}		A or D			y _a		1.4	3.7	6.4		7.6		
^t PHL	SBA or SAB‡	A or B		Ĉ,	b		1.4	4	6.2		6.8	ns	
^t PZH	OEBA	А		200			1	2.9	5.8		7.2		
t _{PZL}	OEBA	A		BA			1	3	6		7.3	ns	
^t PHZ	OEBA	А					2.2	3.9	6.5		6.9		
t _{PLZ}		A					1.8	3.2	5.8		5.9	ns	
^t PZH	OEAB						1	3.3	6.5		7.5		
t _{PZL}		В					1.2	3.4	6.3		7.1	ns	
^t PHZ	OEAB	В					1.7	4.5	7.2		8.1	ns	
t _{PLZ}	OLAB	ט					1.5	3.8	5.8		6.3	115	

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡]These parameters are measured with the internal output state of the storage register opposite to that of the bus input.

SCBS141E - MAY 1992 - REVISED JULY 1995

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \ \Omega$, $t_f \leq 2.5 \ ns$.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



PW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products Applications

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive Communications and Telecom **Amplifiers** amplifier.ti.com www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps

DSP **Energy and Lighting** dsp.ti.com www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical logic.ti.com Logic Security www.ti.com/security

Power Mgmt power.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers <u>microcontroller.ti.com</u> Video and Imaging <u>www.ti.com/video</u>

RFID www.ti-rfid.com

OMAP Applications Processors www.ti.com/omap TI E2E Community e2e.ti.com

Wireless Connectivity <u>www.ti.com/wirelessconnectivity</u>